MATERIAL COMPOSITION DECLARATION

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

RoHS Directive 2002/95/EC and Directive 2011/65/EU with Decision 2010/571/EU (Annex III exemptions) and Decision 2011-534-EU.pdf (new Exemptions)

*Response/Effective Date: 06/10/2015

Supplier Information

*Company Name	*Contact Name	*Phone – Contact	*Email – Contact
Associated Components Technology	Matthew Wang	(714)265-4800	mwang@act1.com
Company Location	*Authorized Representative	*Phone – Representative	*Email – Representative
	Matthew Wang	(714)265-4800	mwang@act1.com

*Mfr Item Number	*Mfr Item Name	Weight	UOM	Unit Type
MTPIxxxx-Series	SMD molding power inductor			

If Manufacturing Information or multiple items are required for the item type contact requester. This form is not acceptable for that information.

***RoHS Material Composition Declaration** | **Company Acceptance: Accepted _x__ Not Accepted ___**

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

- ☒ 1 - Item does not contain RoHS restricted substances per the definition above
- ☐ 2 - Item contains RoHS restricted substances above the limits per the definition above and is not under exemption
- ☐ 3 - Item does not contain RoHS restricted substances per the definition above, except for lead in solders and selected exemptions, if any
- ☐ 4 - Item does not contain RoHS restricted substances per the definition above, except for selected exemptions
- ☐ 5 - Item is obsolete, no information is available
- ☐ 6 - Item is unknown, no information is available

* Required Field

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and select all applicable exemptions.

Exemption List Version - Decision 2010/571/EU

☐ 6(a) Lead as an alloying element in steel containing up to 0.35% lead by weight.

☐ 6(b) Lead as an alloying element in aluminum containing up to 0.4% lead by weight.

☐ 6(c) Lead as an alloying element in copper containing up to 4% lead by weight.

☐ 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)

☐ 7(b) Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.

☐ 7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors**,** e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

☐ 7(c)-II Lead in dielectric ceramic in capacitors for a voltage of 125 V AC or 250 V DC or higher.

☐ 7(c)-III Lead in dielectric ceramic in capacitors for a voltage of less than 125 V AC or 250 V DC.

☐ 7(c)-IV Lead in PZT based dielectric ceramic materials of capacitors being part of integrated circuits or discrete semiconductors.

☐ 8(b) Cadmium and its compounds in electrical contacts

☐ 11(b) Lead used in other than C-press compliant pin connector systems.

☐ 15 Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages.

☐ 39 Cadmium in colour converting II-VI LEDs (< 10 µg Cd per mm2 of light-emitting area) for use in solid state illumination or display systems

If other exemptions are required to be reported please enter them below:

* Required Field

* Declaration Signature	
Instructions: Complete all of the required fields on all pages of this form. Signing this form indicates acceptance of all the information listed in the form. Sign the declaration and submit (email) the form to requester.	
Supplier Signature	Matthew Wang

If Joint Industry Guide information or detailed substance declaration is required per item type contact requester. This form is not acceptable for that information.

* Required Field